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Double Win: Indium Corporation's CW-807RS and Indium12.9HF Receive EM Asia Innovation Honors

CLINTON, N.Y., April 6, 2026 — Indium Corporation®, a leading materials provider for the electronics assembly market, recently received Electronics Manufacturing (EM) Asia Innovation Awards for its halogen-free CW-807RS flux-cored wire and Indium12.9HF solder paste products. A formal presentation ceremony was held at the Productronica China trade show in Shanghai.

CW-807RS improves overall finished quality with soldering performance that aids in creating full, solid solder joints and improves wetting speeds and cycle times for electronics assembly and robotic soldering applications. Its inherent spatter-control and heat-resistance technology combine to improve the cleanliness of the finished assembly and soldering equipment, keeping sensitive components safe from potential harmful solder and flux spattering, even with elevated tip temperatures.

Indium12.9HF is specifically formulated to accommodate fine feature printing, as seen with 01005 components. It offers unprecedented stencil print transfer efficiency, works across a broad range of processes to boost SPI yields, and delivers best-in-class voiding performance, improving thermal management and reliability. In addition, Indium12.9HF demonstrates high oxidation resistance to protect metal surfaces during reflow, ensuring high-quality joints in tough thermal conditions.

"These awards recognize our team's commitment to developing innovative solutions that address real manufacturing challenges," Tim Twining, Indium Corporation Vice President of Sales, Marketing, and Technical Service, said. "Both CW-807RS and Indium12.9HF deliver the performance and reliability that today's electronics applications need, and we're honored that EM Asia has recognized our commitment to moving our industry forward and supporting our customers' success."

Established in 2006, the EM Asia Innovation Award program recognizes and celebrates excellence in the Asian electronics industry, encouraging companies to achieve the highest standards and push the industry forward. The judging panel is composed of process engineering experts from across the OEM/EMS industry with entries evaluated on an exacting criteria, including innovation, cost efficiency, and quality improvement.

To learn more about CW-807RS, Indium12.9HF, and the full portfolio of Indium Corporation's next-generation solder technologies, visit www.indium.com.

Photo: Taylor Wang (right), Associate Director, China Sales, Indium Corporation, accepts the EM Asia Innovation Award for Indium12.9HF solder paste from Cui Yu, IPC East Asia Marketing and Communications Director.

About Indium Corporation

Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit http://www.indium.com/ or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/.

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